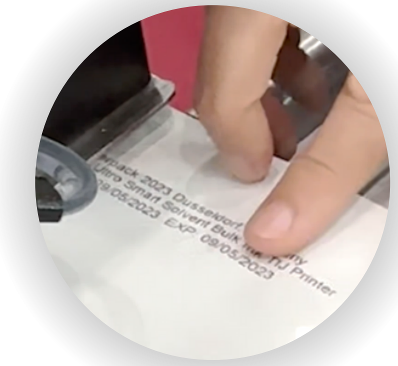
FOR IMMEDIATE RELEASE: 06/08/2023

ANNOUNCEMENT

Funai Microfluidics Solutions Achieves Phenomenal Success at Interpack and Anticipates Breakthroughs at PackExpo

LEXINGTON, KY, USA, June 8, 2023: Funai Microfluidics Solutions (FMS), a global leader in Thermal Inkjet (TIJ) technology for packaging coding and marking, is proud to announce its exceptional reception at Interpack in Düsseldorf, Germany. The event provided an unparalleled platform for Funai to showcase cutting-edge inkjet solutions utilized by FMS's OEM partners.

Interpack was held for the first time in 6 years due to the global pandemic. As an event typically occurring every three years, Interpack is renowned for showcasing the most innovative new products in the packaging technology sector. With attendance reaching 143,000 visitors and 2,800 exhibitors, Interpack proved to be an ideal stage for Funai Microfluidics Solutions to unveil its latest innovations.



Excellent adhesion at long throw distances
Credit; MapleJet Coding & Marking Co.

With the help of several OEM partners demonstrating, Funai showcased solutions that included heavy solvent Bryce cartridges (including bulk delivery), the long-throw heavy solvent Zion cartridges, and its latest product, Sedona aqueous/light solvent 1" (25mm) cartridge.

GMP direct-to-egg printing
Credit; ANSER CODING INC.

"Sedona was designed to fully utilize Funai's patented micro-electromechanical systems (MEMs) that enable industry-leading print quality. Maintaining the redundant rows of nozzles common to all Funai products while increasing the throw distance to 6-8 mm ensures that high speed and high reliability are built into the final product," said Cartridge Development Director Sean Weaver. "It's a very crisp 1" high print."

Long-throw coding on curved substrate
Credit; Rynan Technologies

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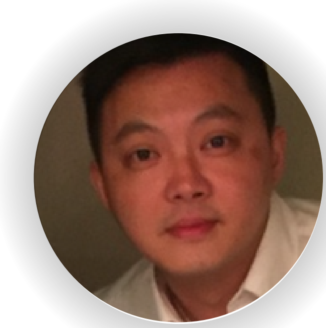
"We received a lot of positive attention at interpack, particularly for Funai's solution. I wanted to share some feedback we received from visitors who expressed interest in your solution.

Food Grade Ink:

I was thrilled to discover Funai's Food-Grade Ink, which perfectly met my printing needs and provided the added assurance of full compliance with food safety regulations for eggshell printing.

10mm Printing Distance:

I'm in search of a coding solution capable of printing on uneven metal surfaces, and the 10mm printing distance solution truly seems like it can assist us."



Denny Chou

Global Sales Director, ANSER CODING INC.

"As one of the proud partners of Funai at Interpack 2023, RYNAN Technologies was thrilled to showcase Funai's groundbreaking 1" Sedona heads with dual nozzle rows for excellent print quality and reliability.

We also showcased our new range of TIJ MEK inks for their Zion cartridges for long throw distance, excellent adhesion, and substrate penetration.

The event provided an opportunity to demonstrate the unparalleled capabilities of Funai's TIJ technology and we are excited about the opportunities it brings to the coding and marking industry.

We look forward to revolutionizing the coding and marking landscape with our innovative offerings and the positive response from visitors experienced at Funai's technology at our booth reaffirmed our belief in Funai's commitment to excellence and advancement."

Bhupinder Singh

VP of Global Sales, RYNAN Technologies

"The best response, from the InterPack Expo, was to Ultro working with Carmel printing with solvent fast dry ink from a distance of 5mm at high speed onto nonporous flexible film and drying in seconds followed by a rub test, live! This was followed by stopping the print for over 10 min and starting up without maintenance, hence a fantastic uptime!

Hx Ultro paired with Funai Zion Bulk solvent cartridges really stood out! High-speed continuous printing, at a 5mm throw distance on non-porous film

Daily we saw familiar faces revisiting our booth. They didn't believe the Hx Ultro printer with Funai solvent bulk cartridges could continuously print at long throw distances and high speed for the duration of the show. I think we gave them a reason to believe!"

Homayoun Shahrestani

Founder & CEO, MapleJet Coding & Marking Co.

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"We are thrilled with the overwhelming response we received at Interpack," said Paul Rahenkamp, FMS Global Sales Director. "The event provided a fantastic opportunity to connect with industry leaders, present our vision for the future of packaging, and showcase our unwavering commitment to delivering exceptional solutions to our customers worldwide."

Building on the success at Interpack, Funai Microfluidics Solutions is eagerly preparing to unveil its latest breakthroughs at the highly anticipated PackExpo in Las Vegas, scheduled for September. Recognized as one of North America's most significant annual packaging events, PackExpo provides Funai the platform to engage with a broader audience and showcase groundbreaking advancements in inkjet technology solutions.

Funai Microfluidics Solutions invites all attendees, partners, and media representatives to visit the FMS PackExpo booth #N-9507 in the PACKage Printing Pavilion (North Hall), Las Vegas, from September 11th to 13th. Experience the future of thermal inkjet printing firsthand, and stay tuned for more updates, product demonstrations, and engaging sessions designed to inspire and inform.

Powered By Funai

Funai focuses on the research and development of thermal inkjet microfluidics for specialty printing, life sciences, and consumer applications. With more than 450 printing-related patents, Funai is recognized as a top-tier microfluidics designer and manufacturer with scaling capabilities to partner with global industries.

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